

Yi Zhang

List of Publications by Year in descending order

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677
citing authors

#	ARTICLE	IF	CITATIONS
1	A Modified Modular Multilevel Converter With Reduced Capacitor Voltage Fluctuation. IEEE Transactions on Industrial Electronics, 2015, 62, 6108-6119.	7.9	94
2	Simplified Thermal Modeling for IGBT Modules With Periodic Power Loss Profiles in Modular Multilevel Converters. IEEE Transactions on Industrial Electronics, 2019, 66, 2323-2332.	7.9	85
3	Seamless Transition Control for Modular Multilevel Converters When Inserting a Cold-Reserve Redundant Submodule. IEEE Transactions on Power Electronics, 2015, 30, 4052-4057.	7.9	83
4	Closed-Loop Precharge Control of Modular Multilevel Converters During Start-Up Processes. IEEE Transactions on Power Electronics, 2015, 30, 524-531.	7.9	73
5	Mission Profile-Based System-Level Reliability Prediction Method for Modular Multilevel Converters. IEEE Transactions on Power Electronics, 2020, 35, 6916-6930.	7.9	50
6	Impact of lifetime model selections on the reliability prediction of IGBT modules in modular multilevel converters. , 2017, , .		44
7	Coordinated Control of Networked AC/DC Microgrids With Adaptive Virtual Inertia and Governor-Gain for Stability Enhancement. IEEE Transactions on Energy Conversion, 2021, 36, 95-110.	5.2	42
8	Condition Monitoring for Submodule Capacitors in Modular Multilevel Converters. IEEE Transactions on Power Electronics, 2019, 34, 10403-10407.	7.9	38
9	Capacitor Condition Monitoring Based on the DC-Side Start-Up of Modular Multilevel Converters. IEEE Transactions on Power Electronics, 2020, 35, 5589-5593.	7.9	33
10	Artificial Intelligence-Aided Thermal Model Considering Cross-Coupling Effects. IEEE Transactions on Power Electronics, 2020, 35, 9998-10002.	7.9	29
11	A Reference Submodule Based Capacitor Condition Monitoring Method for Modular Multilevel Converters. IEEE Transactions on Power Electronics, 2020, 35, 6691-6696.	7.9	25
12	Parameter Estimation of Power Electronic Converters With Physics-Informed Machine Learning. IEEE Transactions on Power Electronics, 2022, 37, 11567-11578.	7.9	19
13	A Viable Mission Profile Emulator for Power Modules in Modular Multilevel Converters. IEEE Transactions on Power Electronics, 2019, 34, 11580-11593.	7.9	17
14	Simplified Multi-time Scale Thermal Model Considering Thermal Coupling in IGBT Modules. , 2019, , .		16
15	The impact of mission profile models on the predicted lifetime of IGBT modules in the modular multilevel converter. , 2017, , .		14
16	A Simplification Method for Power Device Thermal Modeling With Quantitative Error Analysis. IEEE Journal of Emerging and Selected Topics in Power Electronics, 2019, 7, 1649-1658.	5.4	14
17	Computational-Efficient Thermal Estimation for IGBT Modules Under Periodic Power Loss Profiles in Modular Multilevel Converters. IEEE Transactions on Industry Applications, 2019, 55, 4984-4992.	4.9	13
18	An IGBT open-circuit fault detection method for modular multilevel converters. , 2015, , .		11

#	ARTICLE	IF	CITATIONS
19	Balanced Conduction Loss Distribution among SMs in Modular Multilevel Converters. , 2018, , .		11
20	Submodule Level Power Loss Balancing Control for Modular Multilevel Converters. , 2018, , .		11
21	A Comparative Study on the Nonlinear Interaction Between a Focusing Wave and Cylinder Using State-of-the-art Solvers: Part A. International Journal of Offshore and Polar Engineering, 2021, 31, 1-10.	0.8	10
22	Parameter Estimation of Batteries in MMCs with Parallel Connectivity using PSO. , 2021, , .		10
23	Start-up control with constant precharge current for the modular multilevel converter. , 2014, , .		7
24	A multi-port thermal coupling model for multi-chip power modules suitable for circuit simulators. Microelectronics Reliability, 2018, 88-90, 519-523.	1.7	6
25	Comparison and review of DC transformer topologies for HVDC and DC grids. , 2016, , .		5
26	An analytical essential switching loss estimation method for modular multilevel converters with nearest level modulation. , 2017, , .		5
27	A Novel Three-Pulse Equivalent Power Loss Profile for Simplified Thermal Estimation. IEEE Journal of Emerging and Selected Topics in Power Electronics, 2021, 9, 6875-6885.	5.4	5
28	Efficiency Analysis of Conduction Losses in Modular Multilevel Converters with Parallel Functionality. , 2021, , .		5
29	System-Level Power Loss Evaluation of Modular Multilevel Converters. , 2019, , .		4
30	System-Level Thermal Modeling of a Modular Multilevel Converter. , 2020, , .		4
31	Impact of the Thermal-Interface-Material Thickness on IGBT Module Reliability in the Modular Multilevel Converter. , 2018, , .		3
32	Condition Monitoring Method for Submodule Capacitor in Modular Multilevel Converter. , 2019, , .		3
33	Suppression scheme for the common-mode capacitor voltage fluctuations in modular multilevel converters. , 2014, , .		2
34	Precharge strategies for isolated modular DC-DC converters under two different start-up conditions. , 2017, , .		2
35	Simplified Estimation of the Junction Temperature Fluctuation at the Output Frequency for IGBT Modules in Modular Multilevel Converters. , 2018, , .		2
36	Quantitative criteria of considering AC infeed in DC fault assessment of modular multilevel converters. International Journal of Electrical Power and Energy Systems, 2022, 141, 107874.	5.5	2

#	ARTICLE	IF	CITATIONS
37	A Minimum Viable Mission Profile Emulator for IGBT Modules in Modular Multilevel Converters. , 2019, , .		1
38	Lifetime Prediction of the Film Capacitor based on Early Degradation Information. , 2021, , .		1
39	Modulation, Harmonic Analysis, and Balancing Control for a New Modular Multilevel Converter. Journal of Power Electronics, 2016, 16, 163-172.	1.5	1
40	Condition Monitoring for Capacitors in Modular Multilevel Converter based on High-frequency Transient Analysis. , 2021, , .		1
41	An empirical model for thermal interface materials based on experimental characterizations under realistic conditions. Microelectronics Reliability, 2018, 88-90, 806-811.	1.7	0
42	Mission Profile Based Adaptive Carrier Frequency Control for Modular Multilevel Converters for Medium Voltage Applications. , 2019, , .		0
43	DC Fault Current Estimation in a Multi-Terminal Hybrid MMC-HVDC System Considering Fault Ride Through Control. , 2021, , .		0